

Features:

- Isolated mounting base 4000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications:

- Various rectifiers
- DC supply for PWM inverter

V _{RRM}	Type & Outline
2600V	MDx400-26-416F3
2800V	MDx400-28-416F3
3000V	MDx400-30-416F3
3200V	MDx400-32-416F3
3400V	MDx400-34-416F3
3600V	MDx400-36-416F3
3600V	MD400-36-416F3G

MDx stands for any type of **MDC, MDA, MDK**

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =100°C	150			400	A
I _{F(RMS)}	RMS forward current					628	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			50	mA
I _{FSM}	Surge forward current	V _R =60%V _{RRM} ,t=10ms half sine.	150			13	kA
I ² t	I ² t for fusing coordination					845	10 ³ A ² s
V _{FO}	Threshold voltage		150			0.95	V
r _F	Forward slope resistance					0.72	mΩ
V _{FM}	Peak forward voltage	I _{FM} =1200A	25			1.82	V
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled per chip				0.075	°C/W
R _{th(c-h)}	Thermal resistance case to heatsink	Single side cooled per chip				0.024	°C/W
V _{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I _{iso} :1mA(MAX)		4000			V
F _m	Terminal connection torque(M10)			10		12	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T _{vj}	Junction temperature			-40		150	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				1540		g
Outline	416F3						

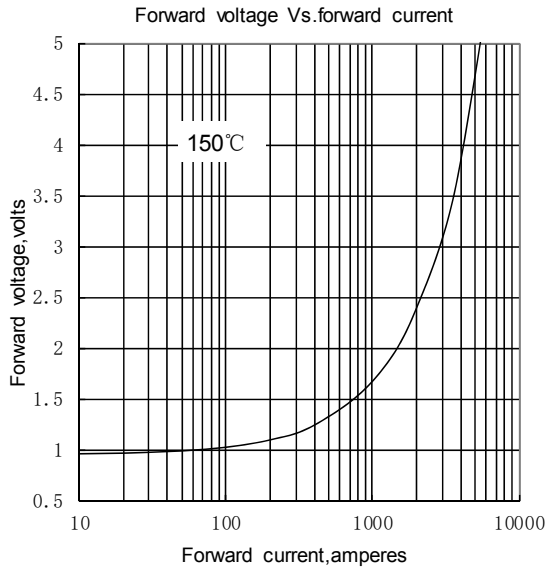


Fig. 1

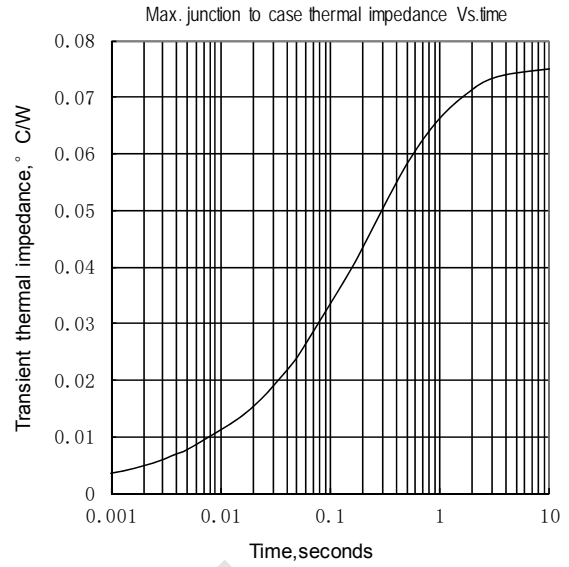


Fig. 2

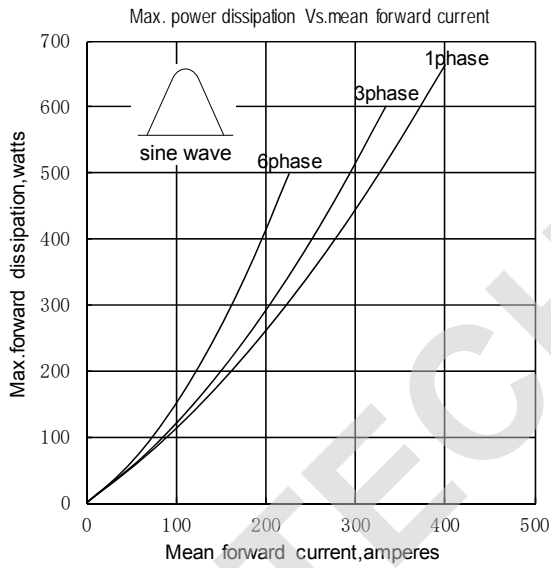


Fig. 3

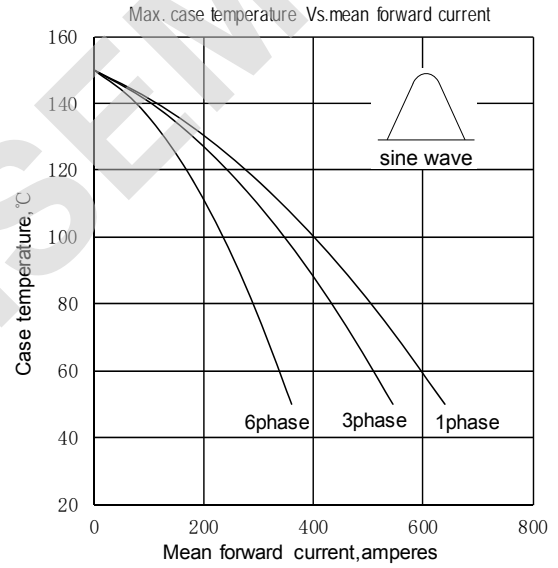


Fig. 4

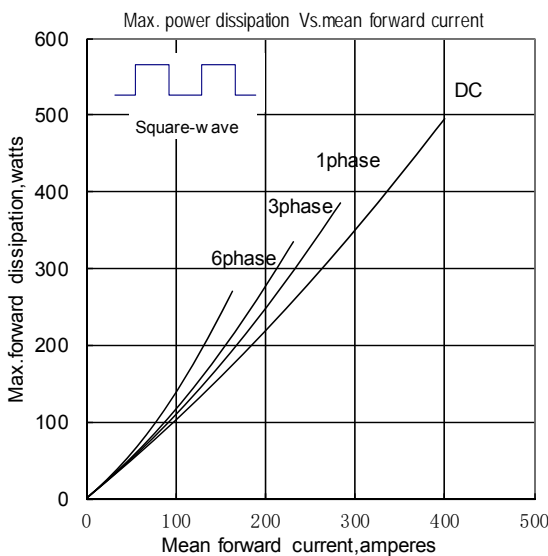


Fig. 5

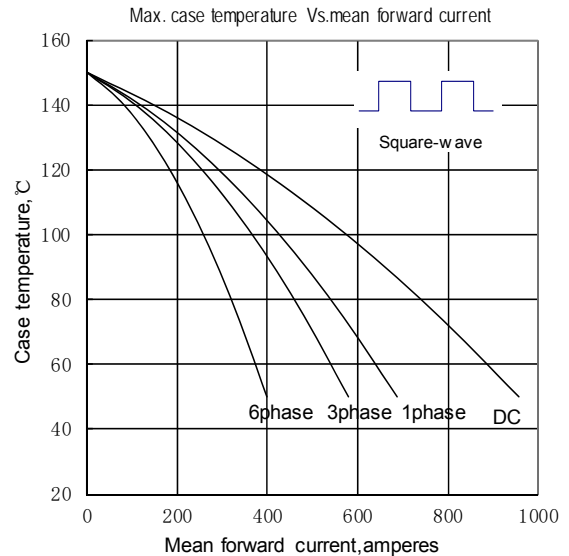


Fig. 6

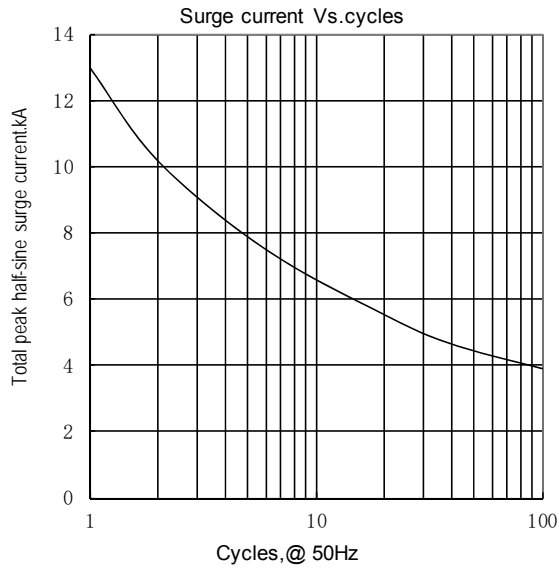


Fig.7

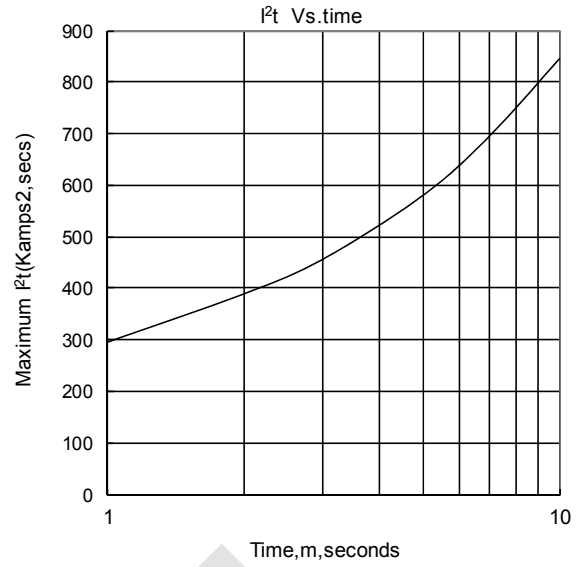
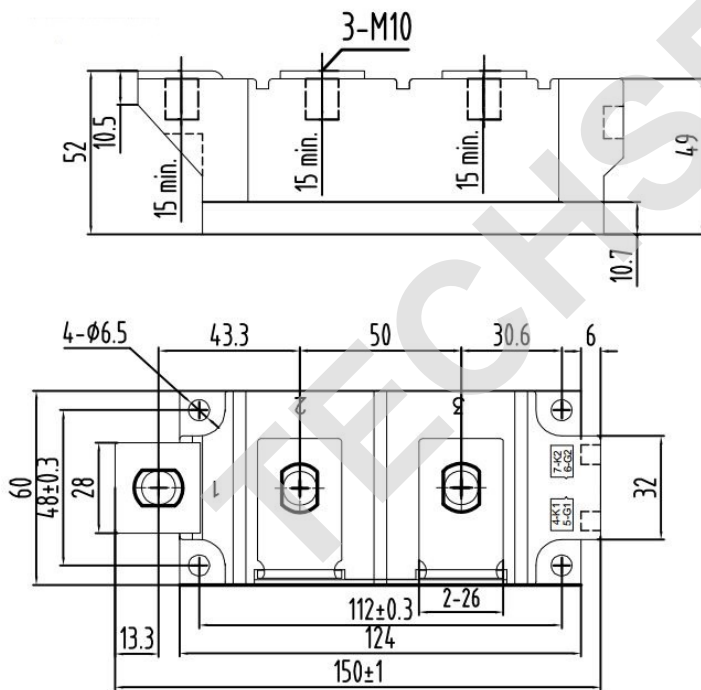


Fig.8

Outline:



Unmarked dimensional tolerance: ±0.5mm

